



Material Content Data Sheet



Sales Product Name	TLE8209-2E			Issued		28. August 2013		
MA#	MA001073678							
Package	PG-DSO-20-71			Weight*		598.32 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	11.544	1.93	1.93	19295	19295
leadframe	inorganic material	phosphorus	7723-14-0	0.051	0.01		85	
	non noble metal	zinc	7440-66-6	0.203	0.03		339	
	non noble metal	iron	7439-89-6	4.058	0.68		6782	
	non noble metal	copper	7440-50-8	164.755	27.54	28.26	275365	282571
wire	non noble metal	copper	7440-50-8	1.590	0.27	0.27	2658	2658
encapsulation	organic material	carbon black	1333-86-4	0.815	0.14		1362	
	plastics	epoxy resin	-	37.486	6.27		62653	
	inorganic material	silicondioxide	60676-86-0	369.158	61.68	68.09	616995	681010
leadfinish	non noble metal	tin	7440-31-5	4.487	0.75	0.75	7499	7499
plating	noble metal	silver	7440-22-4	0.767	0.13	0.13	1282	1282
glue	plastics	epoxy resin	-	0.850	0.14		1421	
	noble metal	silver	7440-22-4	2.551	0.43	0.57	4264	5685
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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